Method and Device for Bonding of Substrates

Abstract

This invention relates to a method for bonding first substrates (2) to second substrates (2 ') with the following features:

- a receptacle for accommodating a carrier substrate (1),
- a placement device for placing multiple first substrates (2) on a substrate side (1s) of the carrier substrate (1) that faces away from the receptacle, and
- a fixing device for fixing each of the first substrates (2) on the substrate side (1s) on at least one fixing section (2a) of each first substrate (2).

Furthermore this invention relates to a method for bonding first substrates (2) to second substrates (2') with the following steps, and especially with the following sequence:

- Placement of multiple first substrates (2) on a substrate side (1s) of a carrier substrate (1) accommodated on a receptacle, and
- Fixing of each first substrate (2) on the substrate side (1s) on at least one fixing section (2a) of each first substrate (2).

Figure 2 ;